


<div>池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD</div>				客户代码 Customer No.	008	线图号 Drawing No.	HY-PX-008-731 A			
焊线图纸 Bonding Diagram				产品名称 Product Type	HS6606		封装外型 PKG Type	SOT25 (20R)		
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)		LF载体尺寸 LF Pad Size		
合金丝 Ag	20	6	6817	1420	442	首选(Preferred): CEL-1702HF 备选(Optional):		SOT23-5L-20R (48×66mil ²) 1230×1680um ²		
客户图号 Customer drawing NO.										

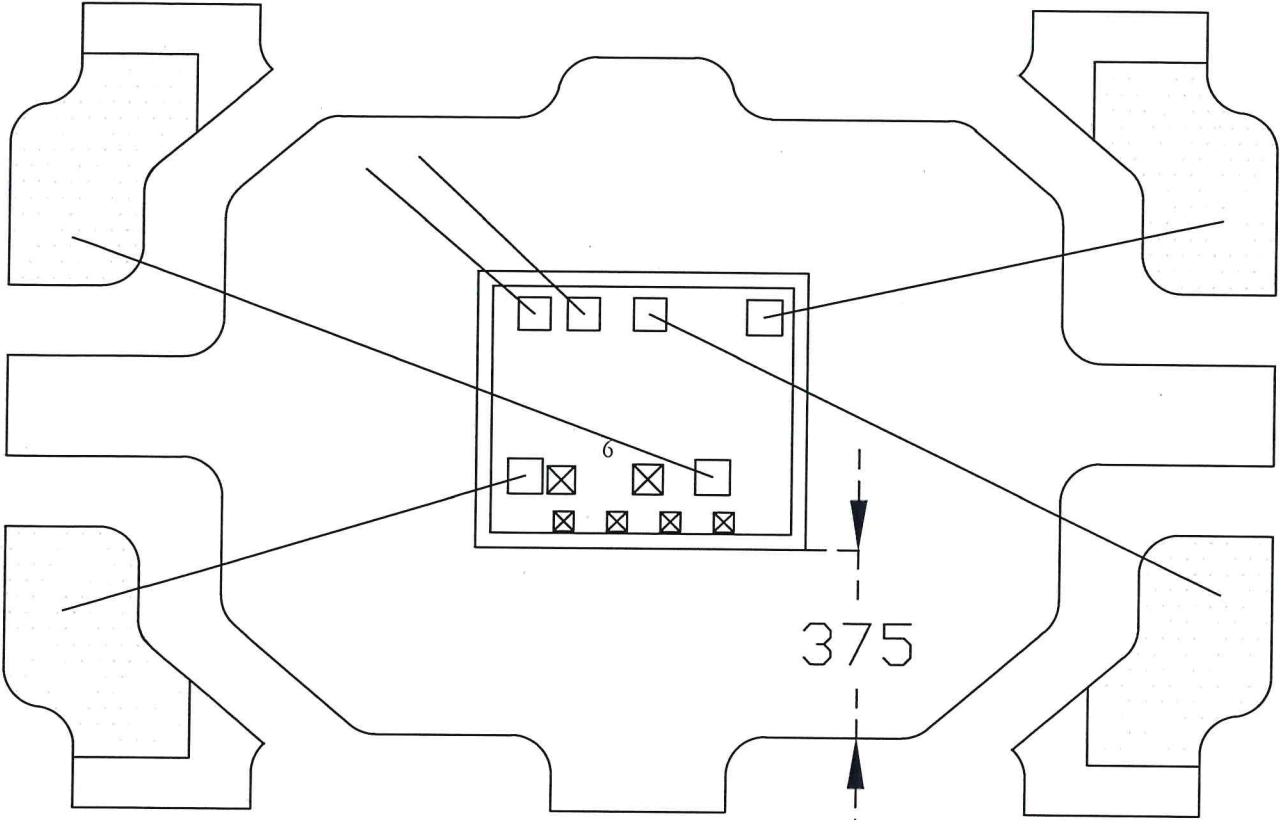
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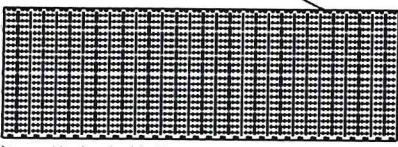
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框架传送方向(载片): L/F Direction (D/A): 椭圆孔				实物图: Chip photo:				特殊说明 Special Instructions: DB注意: 1.芯片左右居中放置; 2.控制溢胶,为WB预留焊线位置; WB注意: 1.数字为不打线pad个数;			
											
注意:基岛全镀银											

说明 Instructions	粘片胶类型 Epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (μm ²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否Low-K If Low-K?	减薄厚度 (μm) Wafer Thinness
A芯: DIE A	导电胶 (conductivity) S210	HS5143	490*602(μm ²) 19.29*23.70(mil ²)	65*65	98	1	是/Yes	60	8	否/NO	230
B芯: DIE B											
C芯: DIE C											

制图日期 Create Date		2024/2/1		生效日期 Effective Date		客户确认签字/盖章: Customer Signature	
拟制 Prepared by	审核 Checked by		批准 Approved by				

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warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce inestimable loss. Thank you

页码 Page
1 / 1